

描述 / Descriptions

TO-220 塑封封装 肖特基二极管，采用新型模具。

Schottky Barrier Diode in a TO-220 Plastic Package, Adopt new mold.

特征 / Features

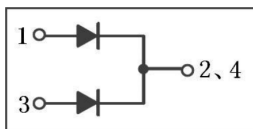
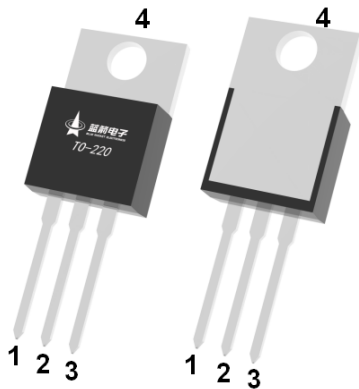
损耗低，效率高，无卤产品。

Low power loss, high efficiency, HF product.

用途 / Applications

用于高频、低压、大电流整流二极管，续流二极管，保护二极管。

For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications.

内部等效电路 / Equivalent Circuit**引脚排列 / Pinning**

PIN1: Anode

PIN 2: Cathode

PIN 3: Anode

印章代码 / Marking

见印章说明。

See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Peak Repetitive Reverse Voltage	V_{RRM}	200	V
Working Peak Reverse Voltage	V_{RWM}	200	V
Average Rectified Output Current @60Hz sine wave,R-load, Ta=25°C	I_O	20	A
Non-Repetitive Peak Forward Surge Current	I_{FSM}	150	A
Current Squared Time @1ms≤t<8.3ms Tj=25°C	I^2T	94	A ² S
Thermal Resistance Junction to Case	$R_{\theta JC}$	2.0	°C/W
Junction Temperature Range	T_j	175	°C
Storage Temperature Range	T_{stg}	-55~175	°C

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Forward Voltage	V_F	$I_F = 10A(T_j = 25^\circ C)$			0.95	V
Instantaneous Reverse Current	I_R	$V_R = 200V(T_j = 25^\circ C)$			0.1	mA
		$V_R = 200V(T_j = 125^\circ C)$			20	mA

电参数曲线图 / Electrical Characteristic Curve

FIG1: I_o - T_c Curve

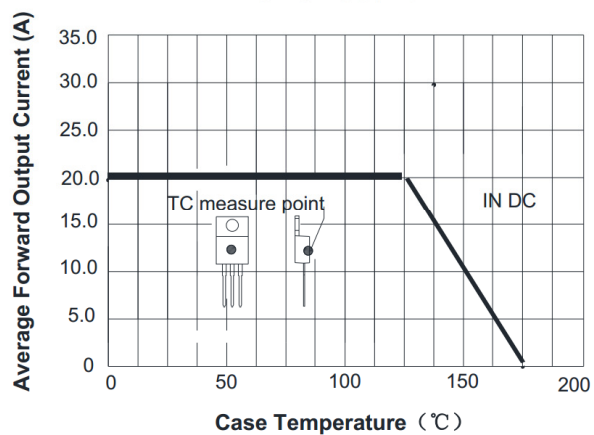


FIG2: Surge Forward Current Capability

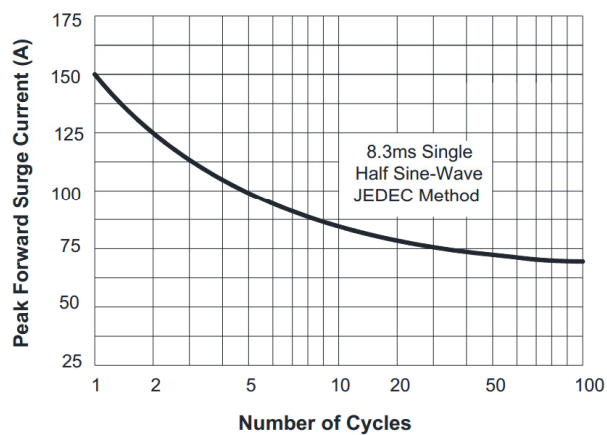


FIG3: Forward Voltage

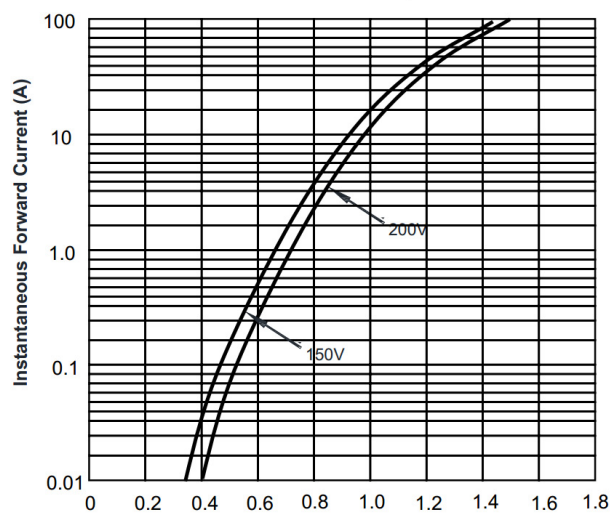
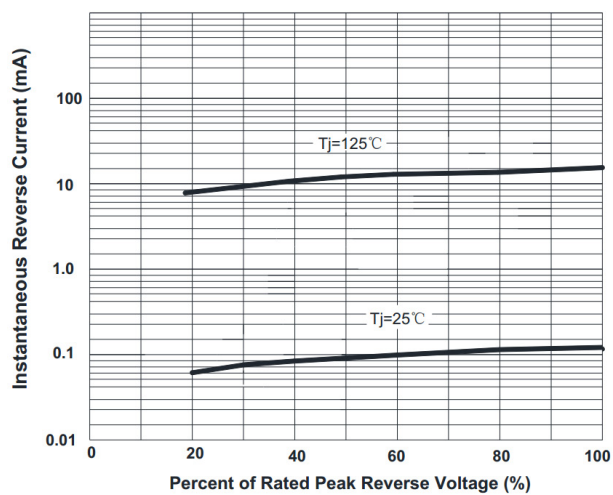
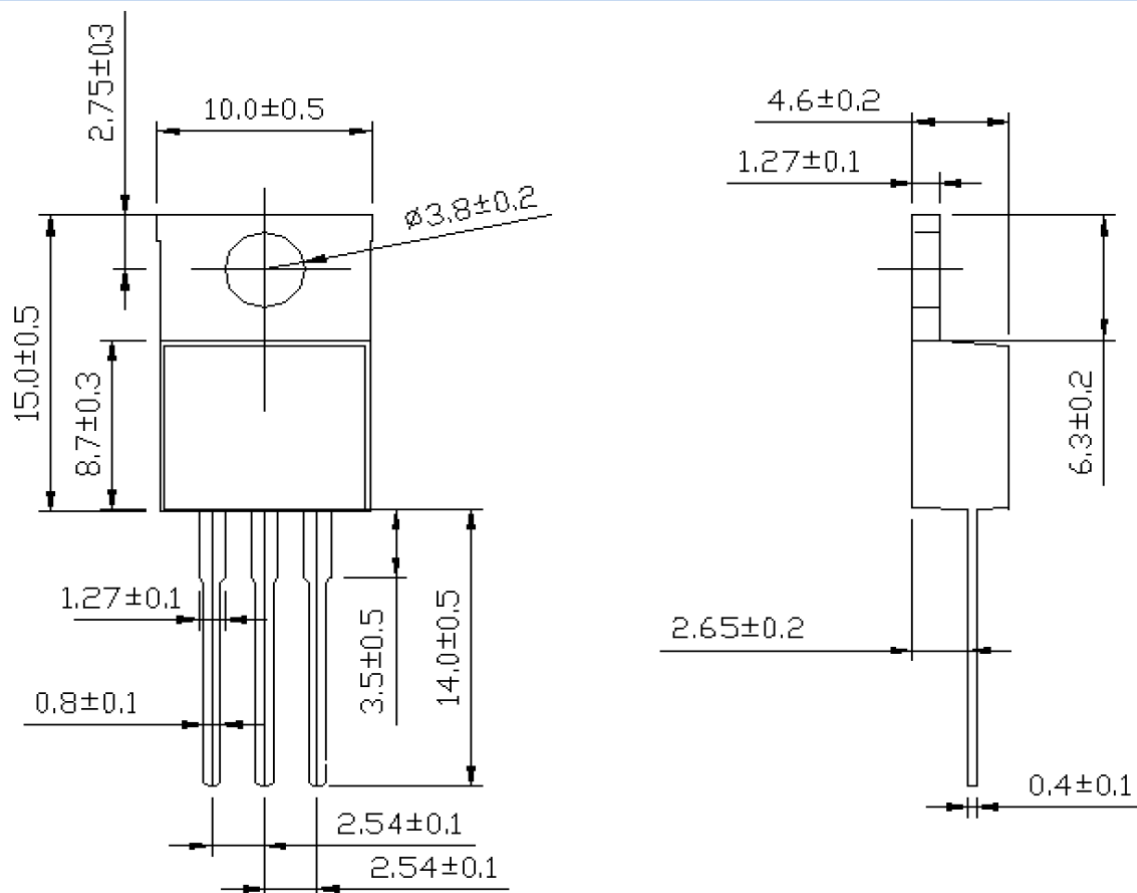


FIG4: Instantaneous Reverse Characteristics

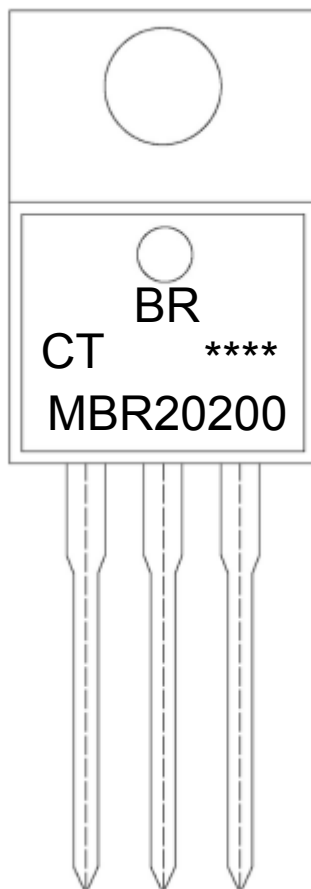


外形尺寸图 / Package Dimensions



Dimensions in millimeters (1mm = 0.0394")

印章说明 / Marking Instructions



说明：

BR： 为公司代码

MBR20200： 为型号代码

CT： 为内部结构

****： 为生产批号代码，随生产批号变化

Note:

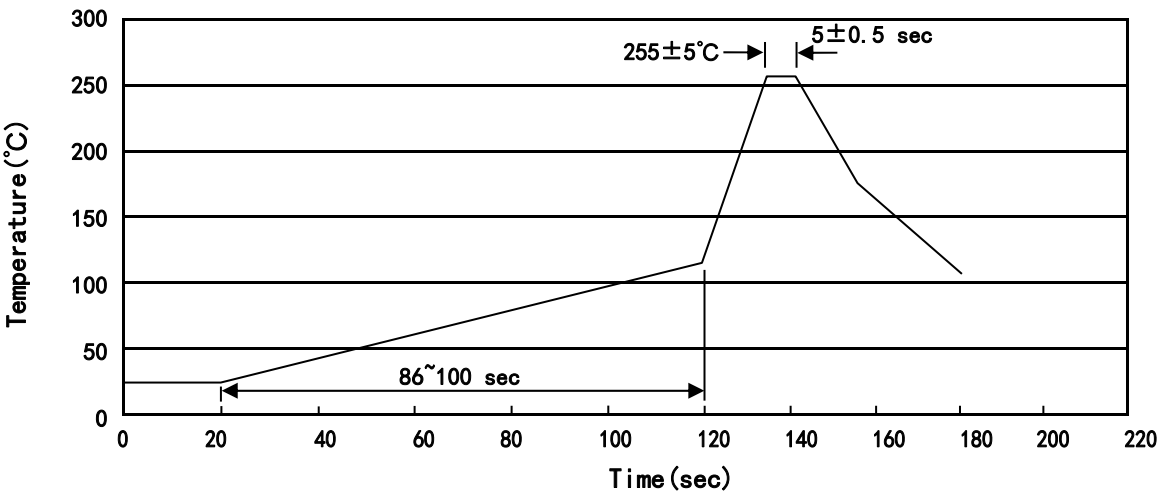
BR: Company Code

MBR20200： Product Type Code

CT: Internal Structure

****: Lot No. Code, code change with Lot No

波峰焊温度曲线图(无铅) / Temperature Profile for Dip Soldering(Pb-Free)



说明：

- 1、预热温度 25 ~ 150℃，时间 60 ~ 90sec;
- 2、峰值温度 255±5℃，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10℃/sec.

Note:

- 1.Preheating:25~150℃, Time:60~90sec.
- 2.Peak Temp.:255±5℃, Duration:5±0.5sec.
3. Cooling Speed: 2~10℃/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：270±5℃ 时间：10±1 sec. Temp.:270±5℃ Time:10±1 sec

包装规格 / Packaging SPEC.

散件包装 / BULK

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Bag 只/袋	Bags/Inner Box 袋/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Bag 袋	Inner Box 盒	Outer Box 箱
TO-220/F	200	10	2,000	5	10,000	135×190	237×172×102	560×245×195

套管包装 / TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Tube 只/套管	Tubes/Inner Box 套管/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Tube 套管	Inner Box 盒	Outer Box 箱
TO-220/F	50	20	1,000	5	5,000	532×31.4×5.5	555×164×50	575×290×180

使用说明 / Notices